

REMARKS

Claims 1-4, 7, 9-14 and 19 are pending. Claims 1-4 have been withdrawn. Claims 7, 9-14 and 19 currently read on the elected species.

Applicants respectfully traverse the finality of the Office Action. The Office Action indicates that Applicants' amendment necessitated the new grounds of rejection. However, Applicants' response filed May 7, 2007 contained no amendments. Therefore, Applicants respectfully request the Examiner to withdraw the finality of the Office action.

The Office Action rejects claims 7, 11 and 14 under 35 U.S.C. § 102(b) over U.S. Patent No. 3,561,107 to Best et al.; rejects claims 7, 11 and 14 under 35 U.S.C. § 103(a) over Best in view of U.S. Patent No. 3,225,511 to Weissenstern; rejects claims 9, 10 and 12 under 35 U.S.C. § 103(a) over Best and Weissenstern and further in view of U.S. Patent No. 4,098,945 to Oehmke; rejects claims 9, 10 and 12 under 35 U.S.C. § 103(a) over Best in view of Oehmke; and rejects claim 13 under 35 U.S.C. § 103(a) over Best or Best in view of Weissenstern. These rejections are respectfully traversed.

Independent claim 7 is directed to a method of manufacturing electronic parts comprising, in combination with other claimed features, providing a holding jig made of elastic material wherein at least one surface of the elastic material is adhesive and mounting a substrate on the holding jig by an adhesive strength of the surface of the elastic material.

Best discloses a method of attaching chips to printed circuits. A dielectric substrate 10 includes a printed circuit, for example, metallic conductive members 12, 14 and 16 formed on the substrate surface. The metallic conductive members

include contact areas 18, 20 and 22 corresponding to contact areas 24, 26 and 28 formed on transistor chip 30. A vibratory member 40 is brought into contact with the chip so that solid conductive pillars 32, 34 and 36 are attached, bonded or welded to the respective contact areas. The Office Action identifies metallic conductive members 12, 14 and 16 as corresponding to the substrate of claim 7. However, the metallic conductive members are a printed circuit and are not mounted on the dielectric substrate 10 by an adhesive surface of the dielectric substrate. Thus, Best does not disclose mounting a substrate on a holding jig by an adhesive strength of an elastic material as in independent claim 7.

Weissenstern is cited to provide the feature of ultrasonic bonding, and thus does not provide the deficiencies of Best relating to the adhesive strength of the elastic material.

The dependent claims are allowable for at least the reasons discussed above as well as for the individual features they recite. For example, new claim 19 recites the adhesive strength of the surface of the elastic material is 1 to 10 g/mm². Furthermore, Applicants respectfully disagree with the Office Action's observation that an ordinarily skilled artisan would have been motivated to combine Best and Oehmke. In particular, one of ordinary skilled would not have been motivated to combine the soft conformable conductive composition of Oehmke with Best because the substrate of Best 10 is dielectric. Thus, Best teaches away from any combination with Oehmke.

Early and favorable action with respect to this application is respectfully requested.

Should any questions arise in connection with this application, or should the Examiner believe that a telephone conference with the undersigned would be helpful in resolving any remaining issues pertaining to this application, the undersigned respectfully requests that he be contacted at the number indicated below.

Respectfully submitted,

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